

RD50 CMOS Meeting

Nissar Karim

16/09/2021



UNIVERSITY OF
LIVERPOOL

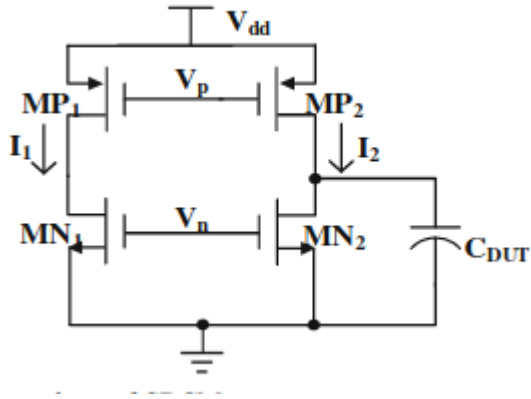


Agendas

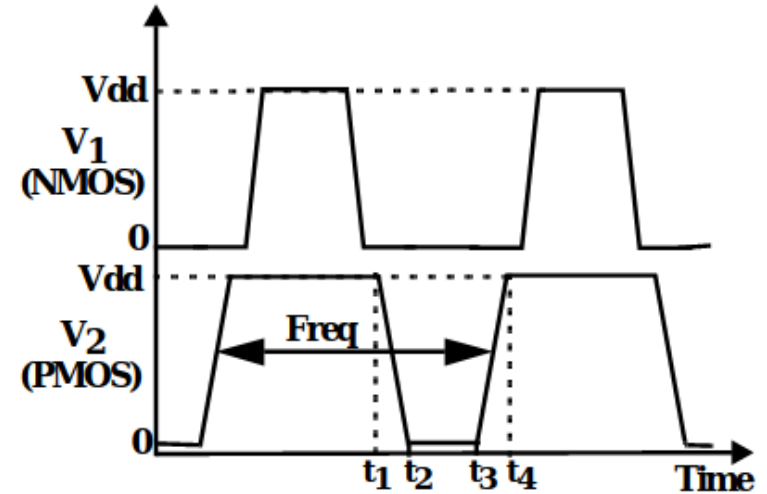
- TestStructure with Capacitor Measurement Circuit
- NMOS Trim DAC Variations
 - NMOS Trim DAC TUNE_IN + TUNE_TH
 - NMOS Trim DAC TUNE_IN
 - NMOS Trim DAC TUNE_TH

TestStructure with Capacitor Measurement Circuit

Theory from Literature



$$C_{DUT} = \frac{(I_1 - I_2)}{V_{dd} \cdot f}$$

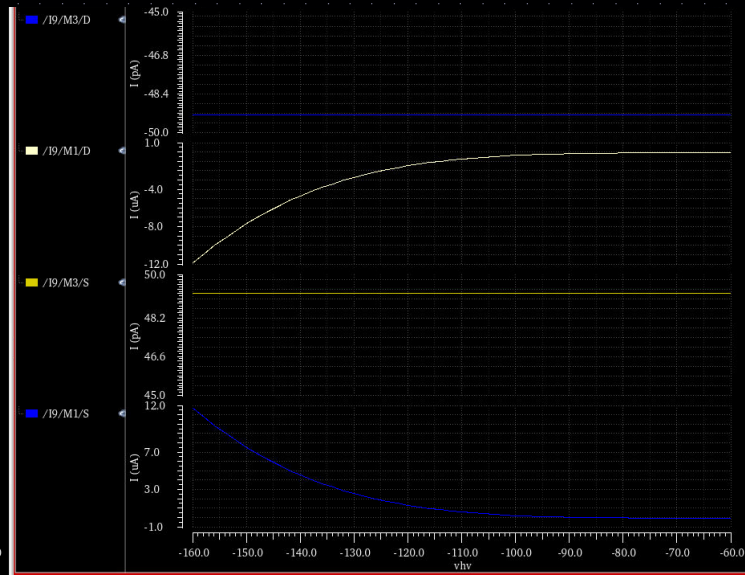
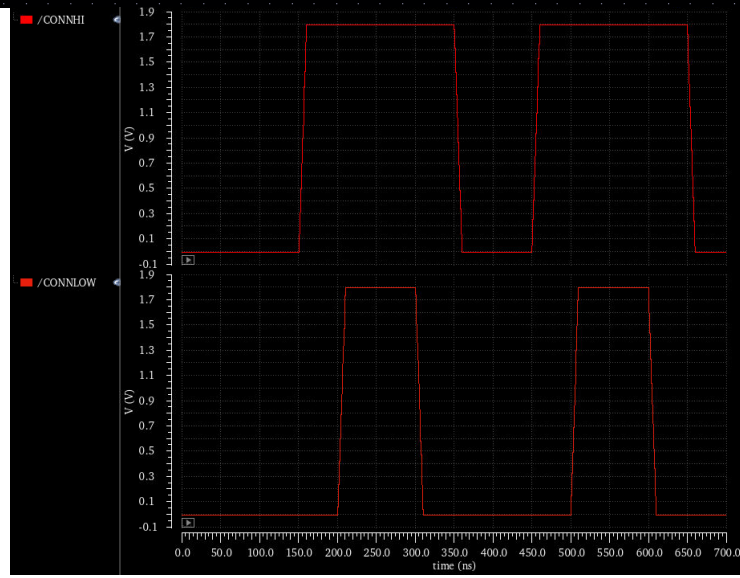
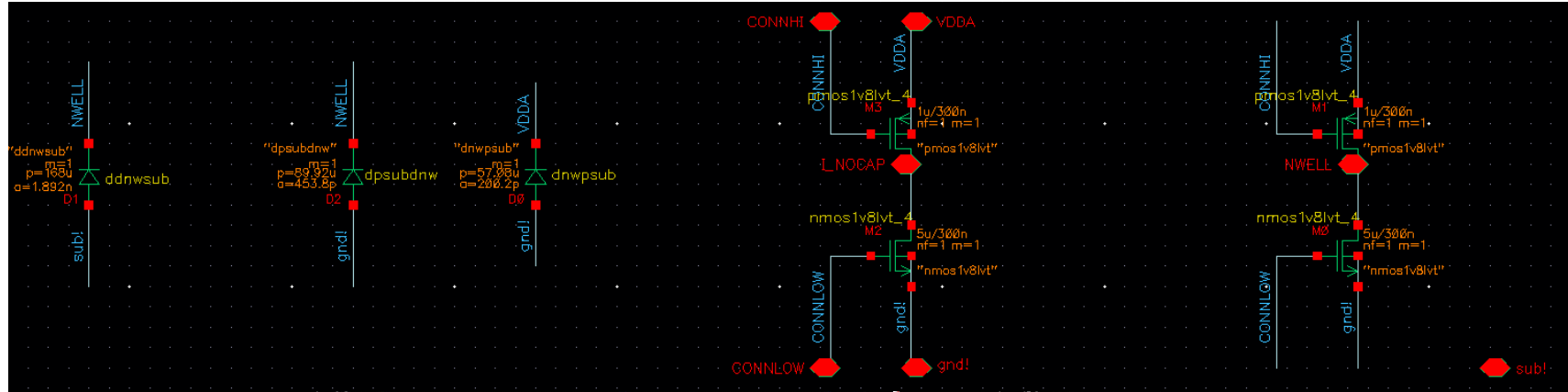


1. Zhu, D., Mo, J., Xu, S., Shang, Y., Wang, Z., Huang, Z., & Yu, F. (2016). A new capacitance-to-frequency converter for on-chip capacitance measurement and calibration in CMOS technology. *Journal of Electronic Testing*, 32(3), 393-397.

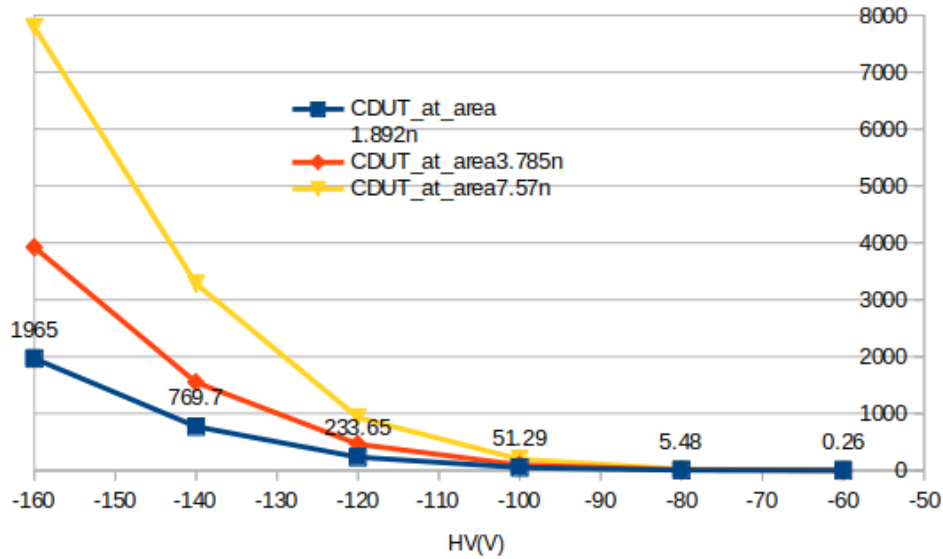
2. Chang, Y. W., Chang, H. W., Lu, T. C., King, Y. C., Ting, W., Ku, J., & Lu, C. Y. (2006). Interconnect capacitance characterization using charge-injection-induced error-free (CIEF) charge-based capacitance measurement (CBCM). *IEEE transactions on semiconductor manufacturing*, 19(1), 50-56.

3. Chen, J. C., McGaughy, B. W., Sylvester, D., & Hu, C. (1996, December). An on-chip, attofarad interconnect charge-based capacitance measurement (CBCM) technique. In *International Electron Devices Meeting. Technical Digest* (pp. 69-72). IEEE.

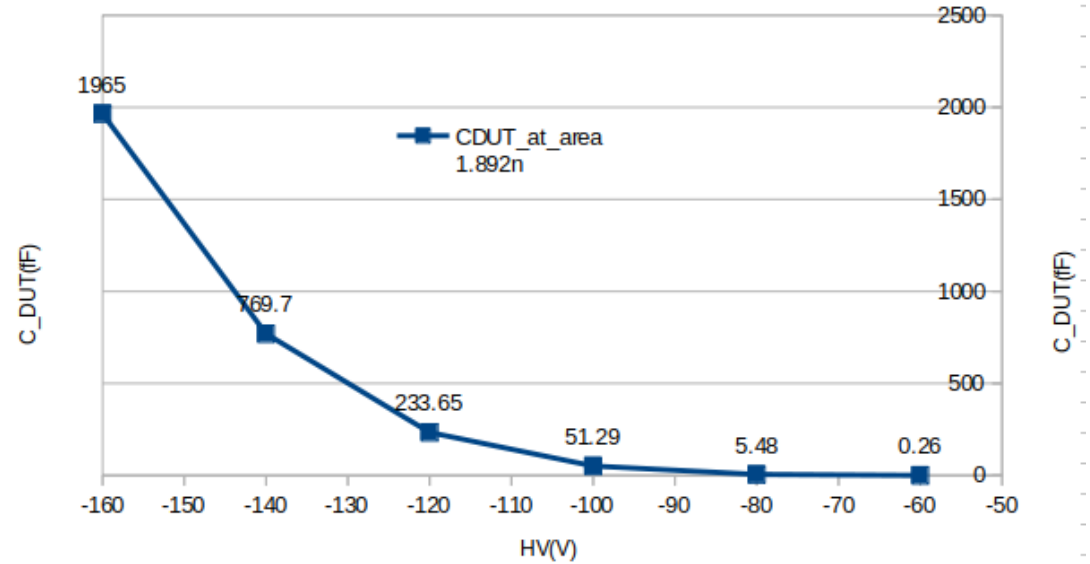
Schematic & Simulation Waveforms



HV(V) vs. Capacitance of the NWEELL



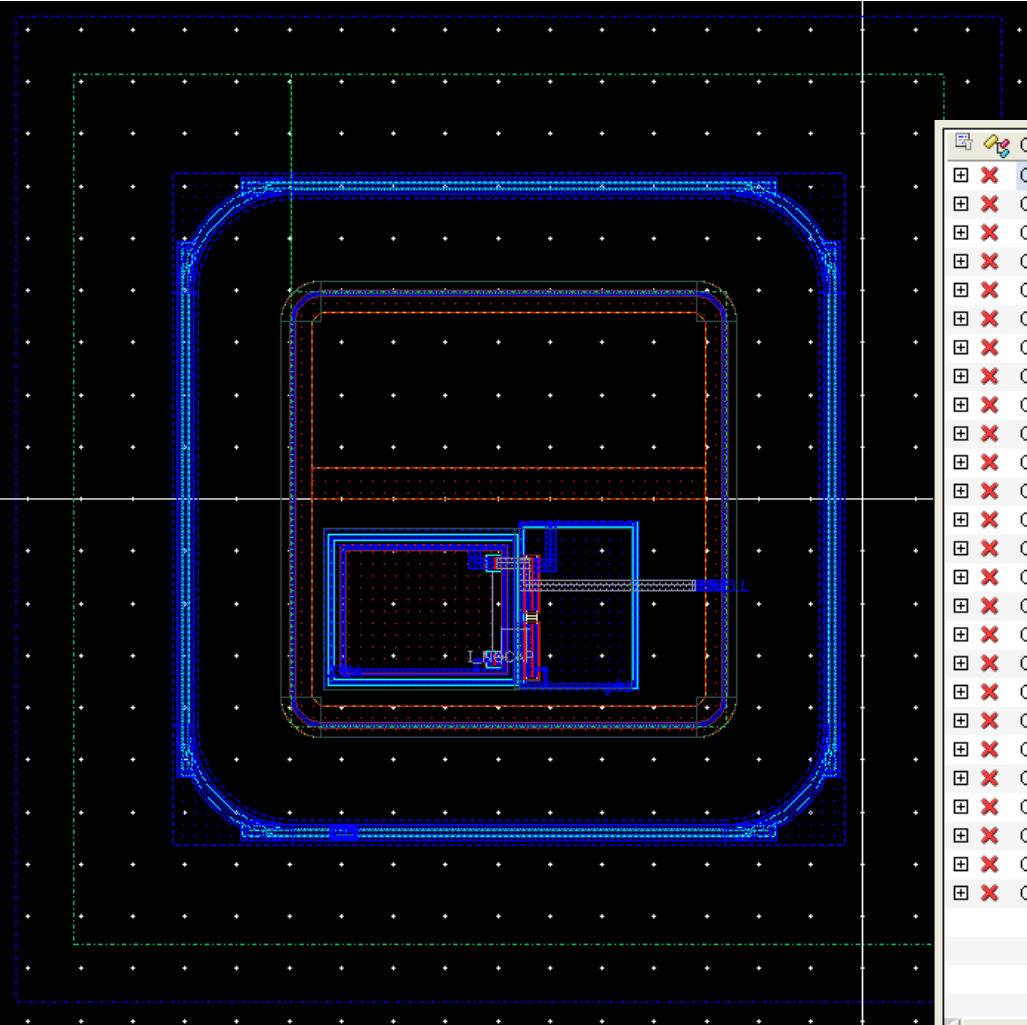
Considering different arbitrary areas to check if C_DUT changes with area



Considering the area in the designed teststructure

Note: The area corresponds to ddnwsub

Verifications



Check / Cell	Results
<input checked="" type="checkbox"/> Check METAL1.WIDTH	4
<input checked="" type="checkbox"/> Check DNWRING.WIDTH	8
<input checked="" type="checkbox"/> Check NISO.WIDTH	8
<input checked="" type="checkbox"/> Check NISO_recommended.CLEARANCE.UC.NWELL	2
<input checked="" type="checkbox"/> Check PWELL.WIDTH	6
<input checked="" type="checkbox"/> Check PWELL_C.WIDTH	6
<input checked="" type="checkbox"/> Check DNWELL.NEED.PSUB	2
<input checked="" type="checkbox"/> Check DNWELL10.OVERLAP.NISO10	4
<input checked="" type="checkbox"/> Check DNWELL10.OVERLAP.NWELL10	4
<input checked="" type="checkbox"/> Check NISO.OVERLAP.NWELL	4
<input checked="" type="checkbox"/> Check DIF.MINDENS.1	1
<input checked="" type="checkbox"/> Check DIF.MINDENS.2	1
<input checked="" type="checkbox"/> Check POL.MINDENS.1	1
<input checked="" type="checkbox"/> Check POL.MINDENS.2	1
<input checked="" type="checkbox"/> Check ME1.MINDENS.1	1
<input checked="" type="checkbox"/> Check ME1.MINDENS.2	1
<input checked="" type="checkbox"/> Check ME2.MINDENS.1	1
<input checked="" type="checkbox"/> Check ME2.MINDENS.2	1
<input checked="" type="checkbox"/> Check ME3.MINDENS.1	1
<input checked="" type="checkbox"/> Check ME3.MINDENS.2	1
<input checked="" type="checkbox"/> Check ME4.MINDENS.1	1
<input checked="" type="checkbox"/> Check ME4.MINDENS.2	1
<input checked="" type="checkbox"/> Check ME5.MINDENS.1	1
<input checked="" type="checkbox"/> Check ME5.MINDENS.2	1
<input checked="" type="checkbox"/> Check MEF.MINDENS.1	1
<input checked="" type="checkbox"/> Check MEF.MINDENS.2	1

Cell DIODE_CAP_MEAS_four_transistor Summary (Clean)

CELL COMPARISON RESULTS (TOP LEVEL)

```

#####
#          #
#   CORRECT   #
#          #
#####
  
```

LAYOUT CELL NAME: DIODE_CAP_MEAS_four_transistor
SOURCE CELL NAME: DIODE_CAP_MEAS_four_transistor

NUMBERS OF OBJECTS

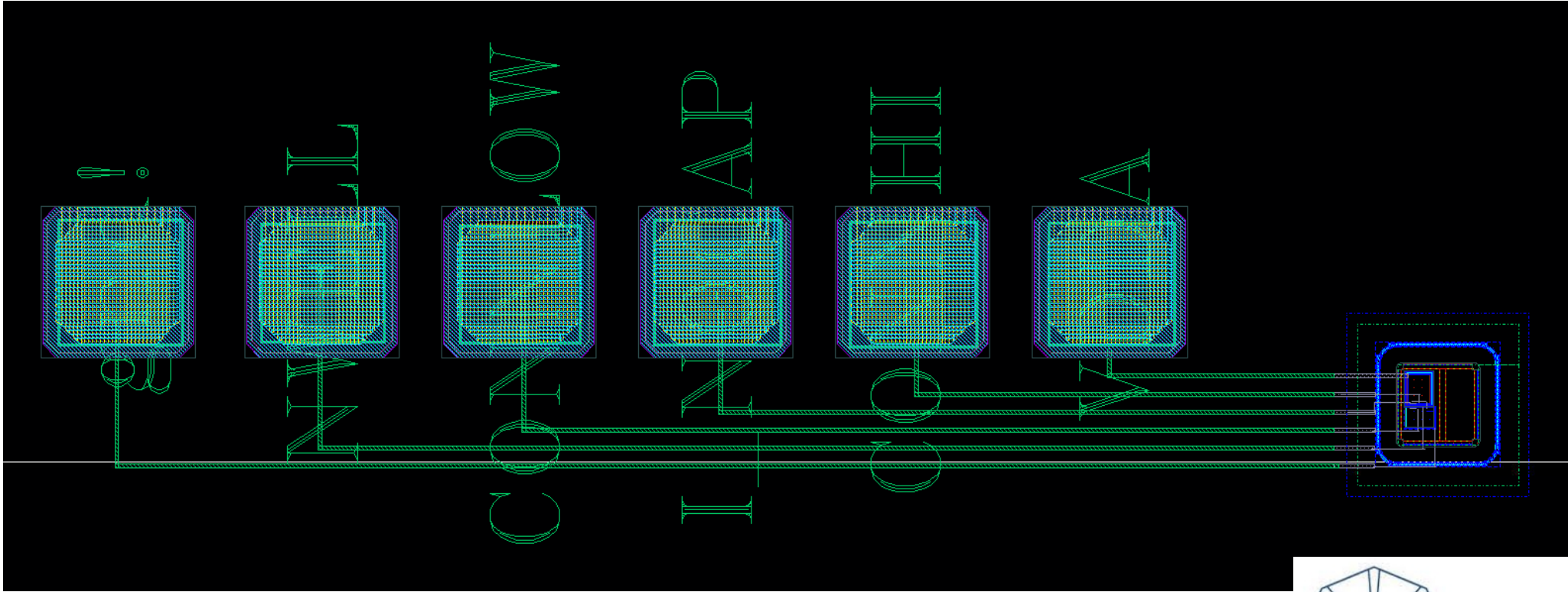
	Layout	Source	Component Type
Ports:	7	7	
Nets:	7	7	
Instances:	2	2	MN (4 pins)
	2	2	MP (4 pins)
	3	3	D (2 pins)
Total Inst:	7	7	

INFORMATION AND WARNINGS

Cell DIODE_CAP_MEAS_four_transistor (Stamping conflict #1)

Warning: #1 in DIODE_CAP_MEAS_four_transistor
WARNING: Stamping conflict in SCONNECT - Multiple source nets stamp one target net.
Use LVS REPORT OPTION S or LVS SOPTCHK statement to obtain detailed information.

With PAD Connections

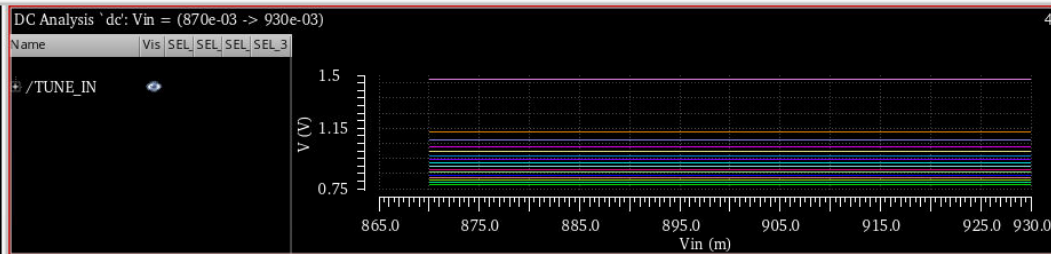
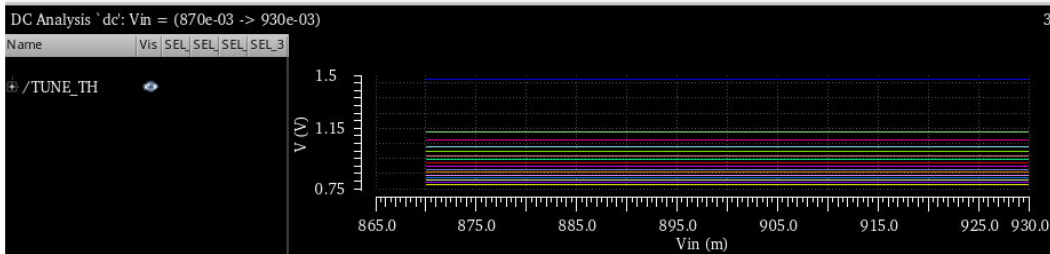
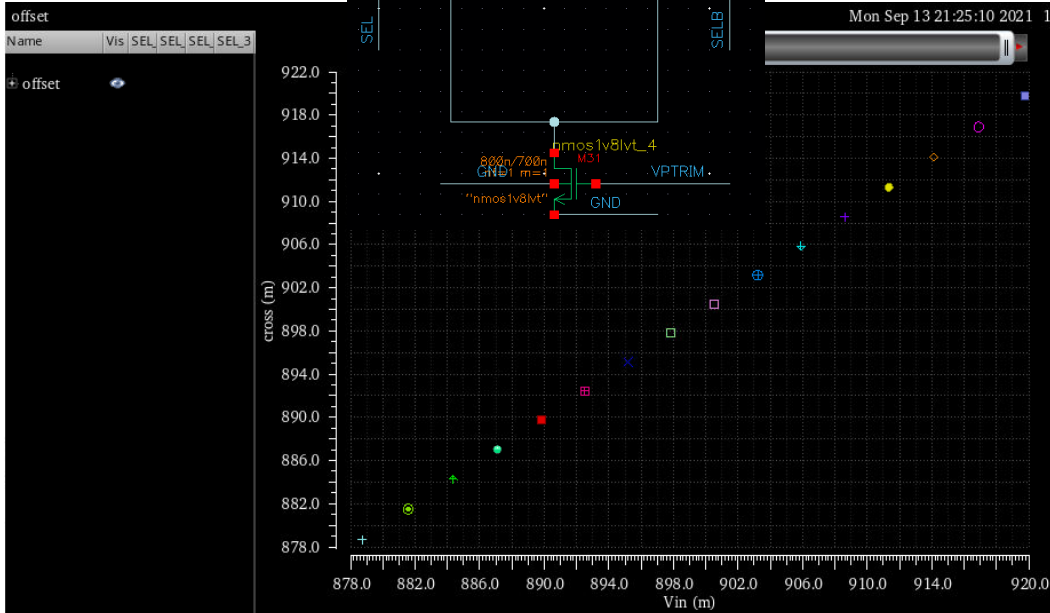
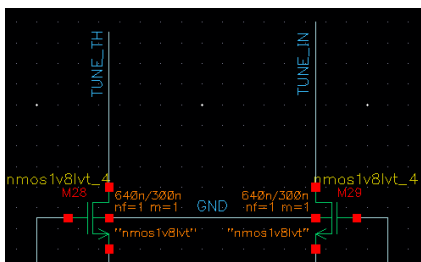


NMOS Trim DAC Variations

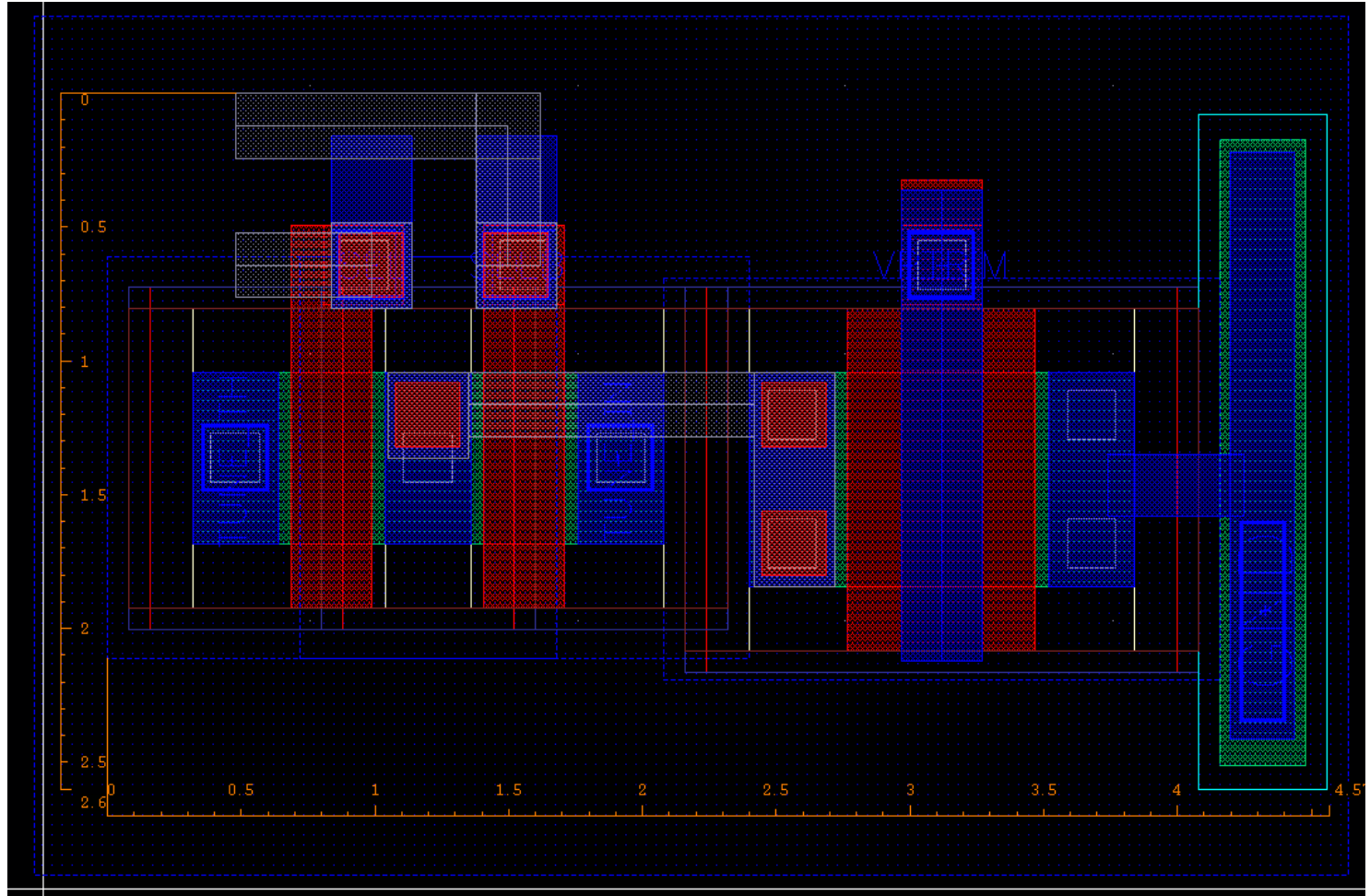
NMOS TRIM-DAC Cell with only TUNE_IN & TUNE_TH

Number = 300
 Mean = 898.662m
 Std Dev = 6.86279m

3Xstd dev=20.58



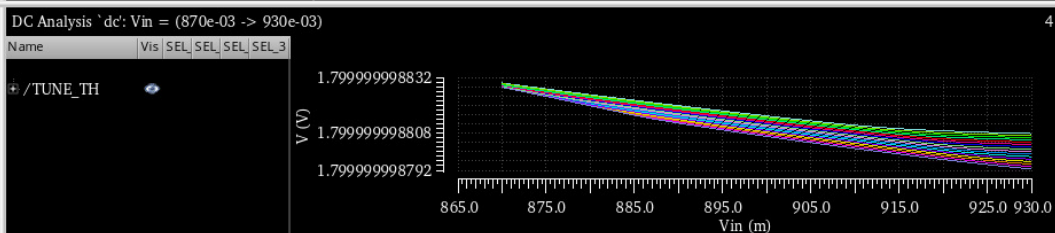
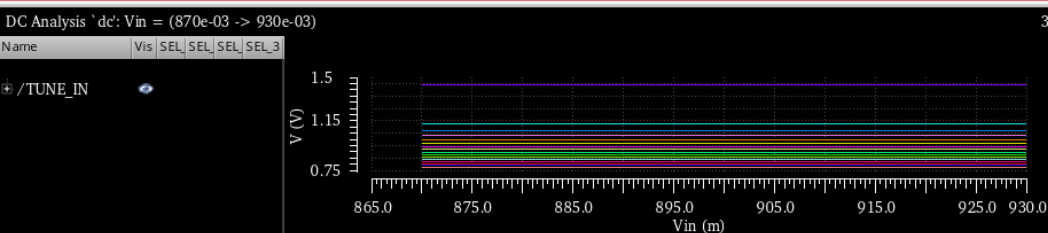
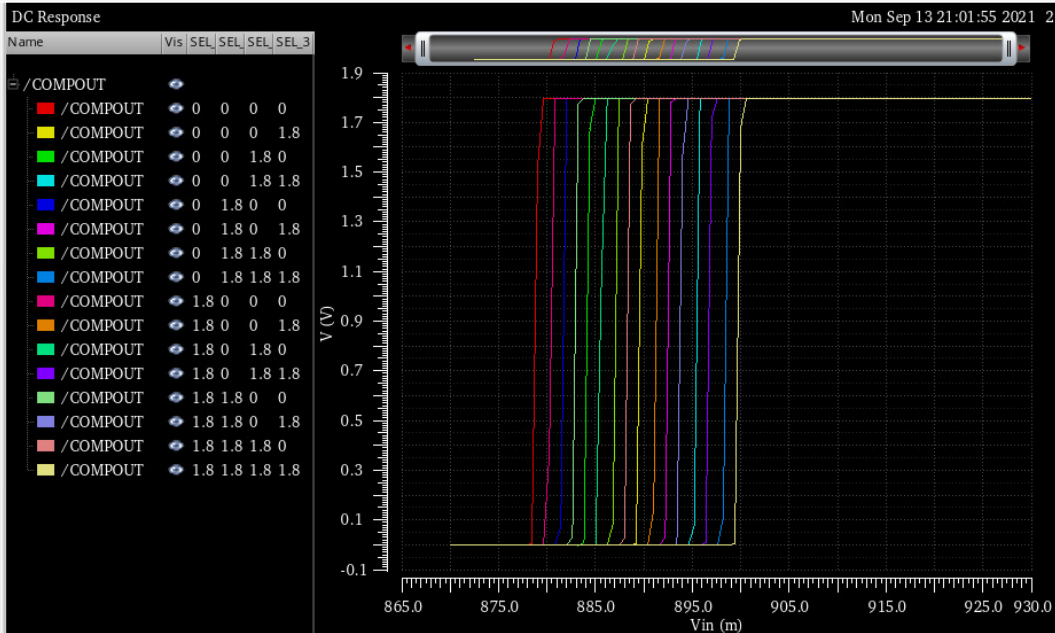
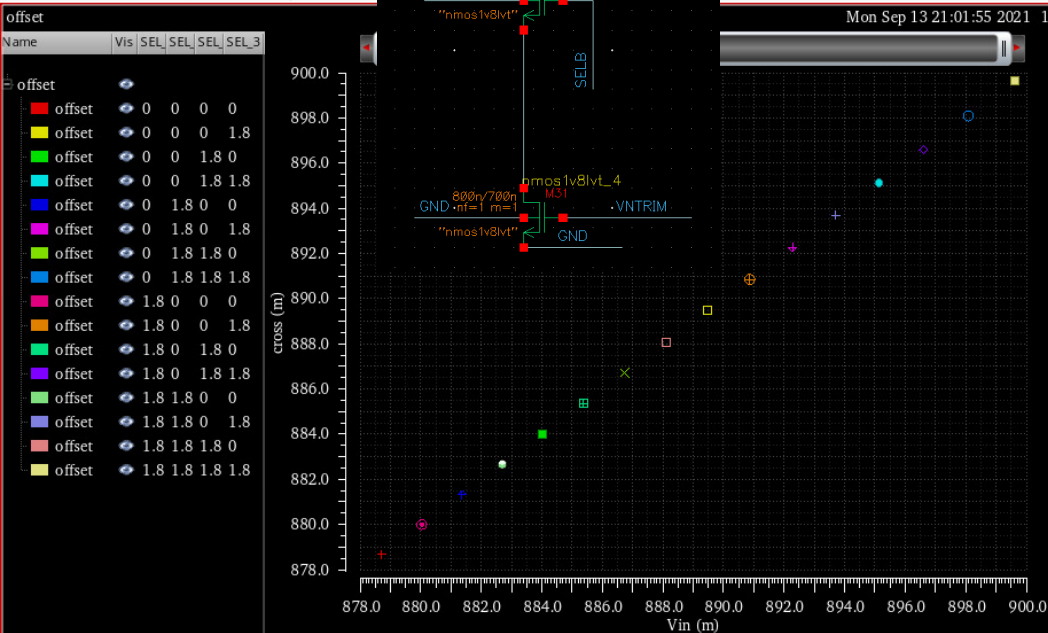
NMOS TRIM-DAC Cell with only TUNE_IN & TUNE_TH (LAYOUT)



NMOS TRIM-DAC Cell with only TUNE_IN

Number = 300
 Mean = 898.662m
 Std Dev = 6.86279m

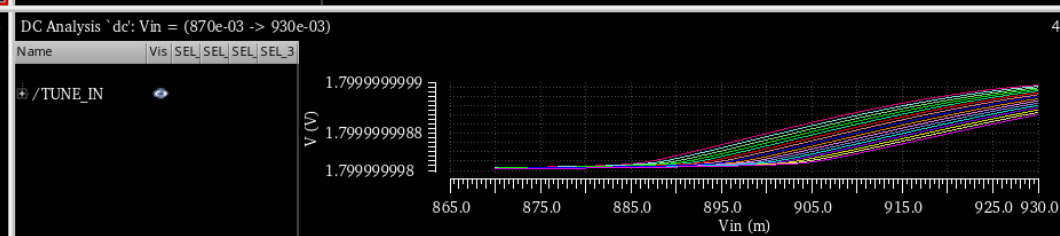
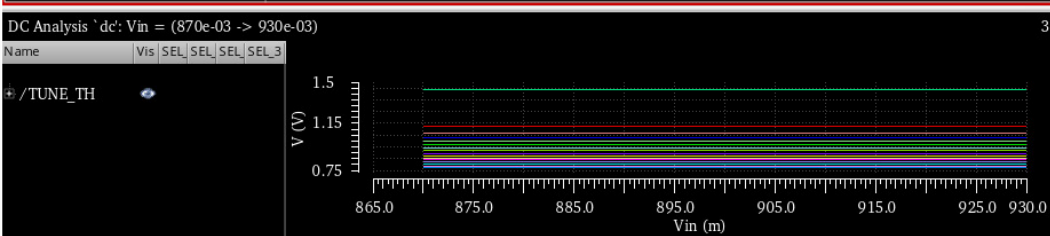
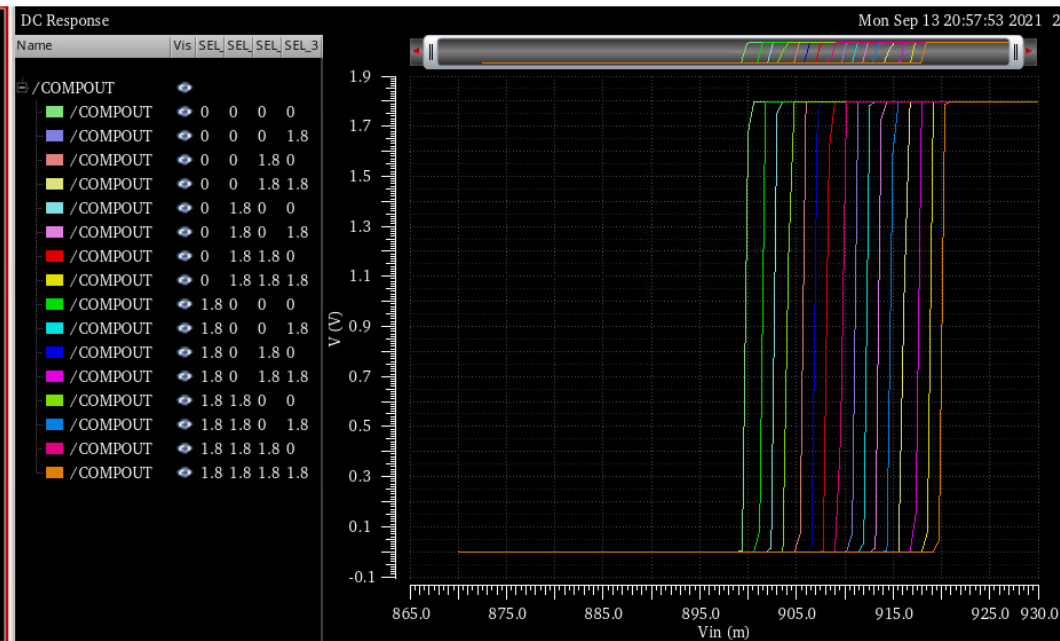
3Xstd dev=20.58



NMOS TRIM-DAC Cell with only TUNE_TH

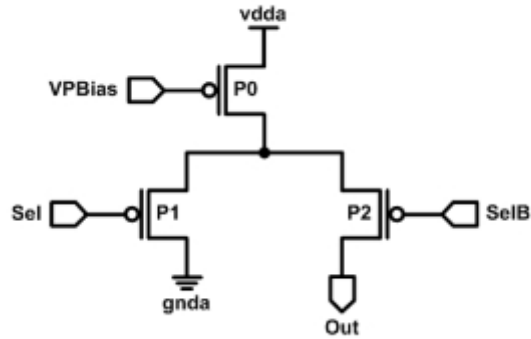
Number = 300
 Mean = 898.662m
 Std Dev = 6.86279m

3Xstd dev=20.58



THANK YOU

H35DEMO



TUNE_IN is used here since OUT is from SELB.